### T-1 3/4 (5mm) VARIABLE HEIGHT LED BOARD INDICATOR

Part Number: L-7113BR-5.08/ID

High Efficiency Red

#### Features

• LED firmly held by spacer-no additional fixturing or glueing necessary.

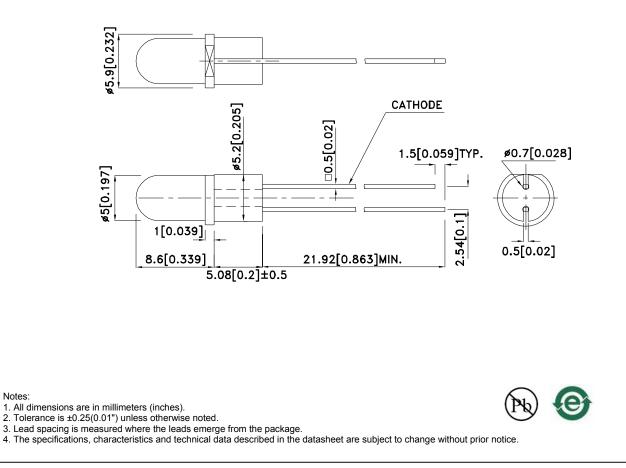
• Suitable for back panel illumination, circuit board indicator, LED indicator.

- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### Package Dimensions



SPEC NO: DSAE7400 APPROVED: WYNEC REV NO: V.10 CHECKED: Allen Liu DATE: DEC/27/2010 DRAWN: C.H.Han PAGE: 1 OF 5 ERP: 1102001473

#### **Selection Guide** lv (mcd) [2] Viewing @ 10mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. L-7113BR-5.08/ID High Efficiency Red (GaAsP/GaP) Red Diffused 25 50 30°

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	IF=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I⊧=20mA
IR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

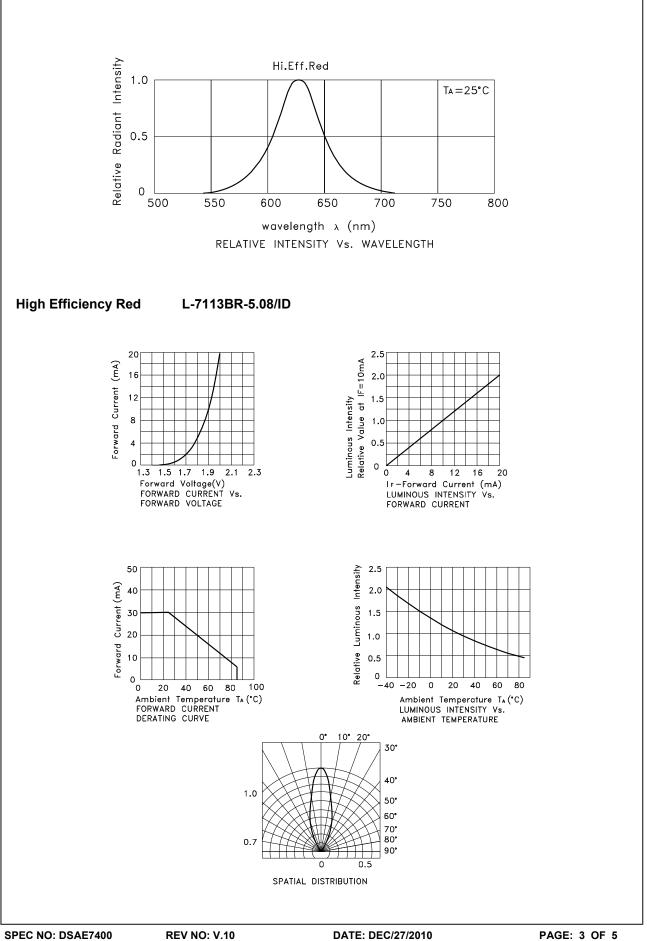
Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

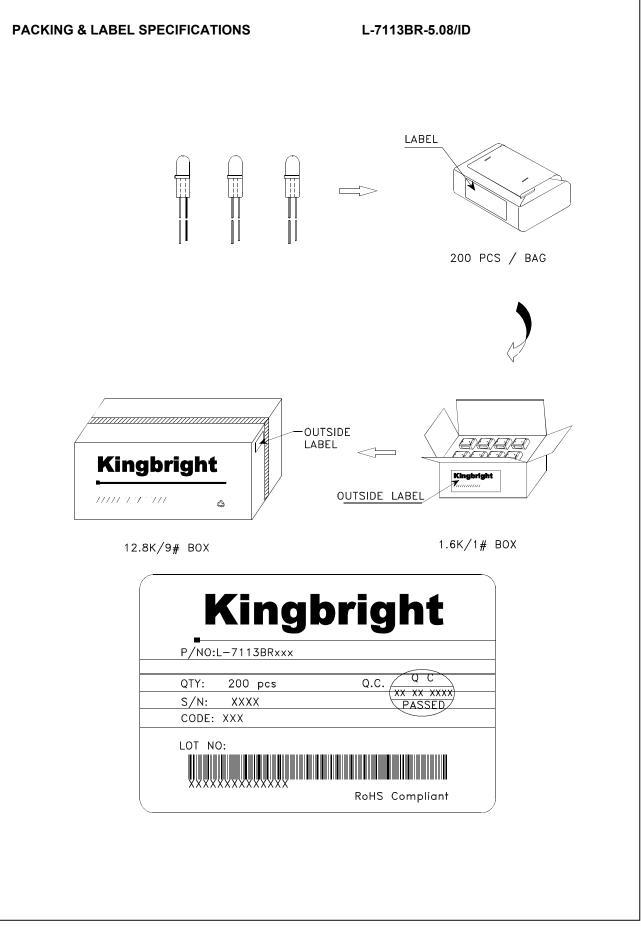
#### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red			
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	160	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

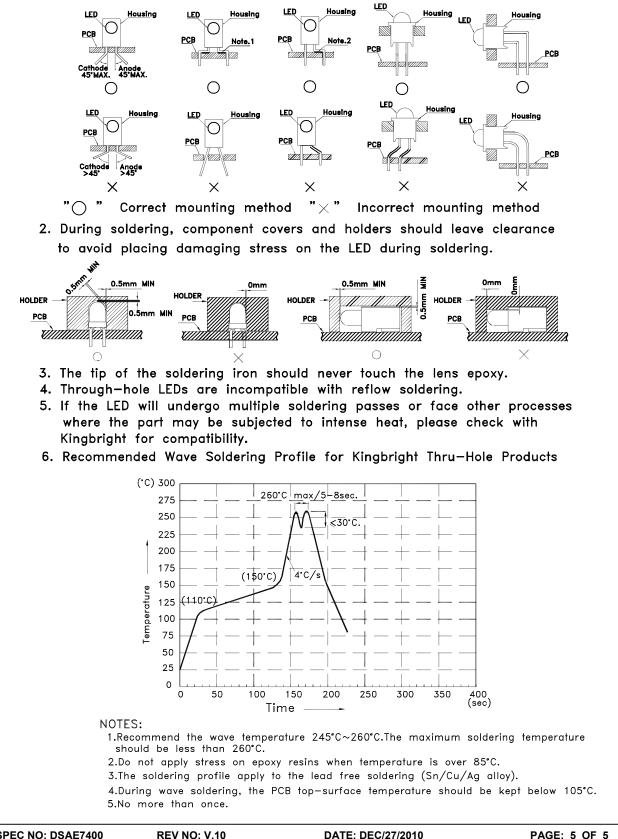
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DATE: DEC/27/2010 DRAWN: C.H.Han